

IN THE SPECIFICATION:

Please replace page 7, first full paragraph, with the following:

Fig. 1A shows a printed wiring board of an embodiment of the invention.

Fig. 1B shows a making a hole in the printed wiring board of Fig. 1A.

Fig. 1C shows plating on the sides of the hole in Fig. 1B.

Fig. 1D shows adding photoresist to the top and bottom of the printed wiring board in Fig. 1C.

Fig. 1E shows removing photoresist adjacent the hole in Fig. 1D.

Fig. 1F shows the hole of Fig. 1E filled with conductor.

Fig. 1G shows the printed wiring board of Fig. 1F with the photoresist removed.